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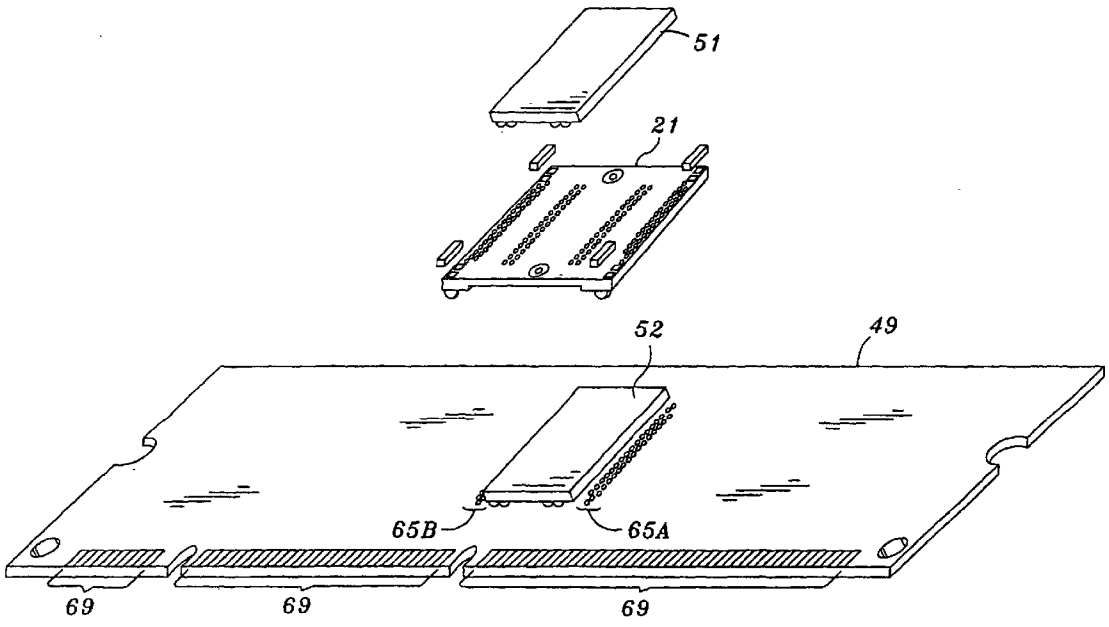
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(54) Title: A MODULAR INTEGRATED CIRCUIT CHIP CARRIER



(57) Abstract: An apparatus and method is disclosed that allows for the arranging in a three dimensional array semiconductor chips on a circuit board. A unique chip carrier is disclosed on which any IC chip can be positioned on above the other on a circuit board. Additionally, the carrier allows for the testing of IC chips on the carrier and underneath it without having to remote the carrier and chips from the system even if they are of the BGA or CSP type. The carrier includes exposed test points to allow an on site test.

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